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Atty. Docket: 10191/1466

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**GROUP 1700**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Volker BECKER, *et al.*  
Serial No. : 09/581,663  
Filed : August 3, 2000  
For : METHOD FOR PROCESSING SILICON  
BY ETCHING PROCESSES  
Group Art Unit : 1746  
Examiner : S. AHMED

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
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Signature: [Signature]  
Jong H. Lee

**SUPPLEMENTAL AMENDMENT AFTER FINAL REJECTION**  
**UNDER 37 C.F.R. § 1.116**

SIR:

In response to the Final Office Action dated July 5, 2002, please amend the above-identified application, as set forth below. Entry of the amendment is requested since it raises no new issue and merely puts an objected-to claim in condition for allowance.

**IN THE CLAIMS:**

Please amend claims 53 and 63 as follows:

53. (Amended) A method for etching a silicon layered body, which has a first silicon layer (15) that is provided with an etching mask (10) for defining lateral